

An IATF 16949, ISO9001 and ISO 14001/ISO 45001 Certified Company





## 1.0A SURFACE MOUNT SCHOTTKY RECTIFIERS

**DSK12~DSK120** 



SOD-123 FL

SOD-123FL Surface Mount Plastic Package RoHS compliant

#### **Features**

- 1. Surface Mount Application
- 2. Low Forward Voltage Drop
- 3. Low Reverse Leakage
- 4. High Forward Surge Current Capability
- 5. The Plastic Package Carries Underwriters Laboratory Flammability Classification 94V-O.
- 6. High Temperature Soldering Guaranteed: 250°C/10 seconds at Terminals
- 7. Weight: 0.02 grams

Applications: Power supply, LED drivers







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### ABSOLUTE MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at T<sub>A</sub>=25°C Ambient Temperature unless otherwise specified. Single Phase Half-Wave 60Hz,Resistive or Inductive Load. For Capacitive Load Current Derate by 20%)

PARAMETER		SYMBOL	DSK 12	DSK 14	DSK 16	DSK 18	DSK 110	DSK 115	DSK 120	Unit
		Marking Code	K12	K14	K16	K18	K110	K115	K120	Offic
Maximum Repetitive Peak Reverse Voltage		$V_{RRM}$	20	40	60	80	100	150	200	V
Maximum RMS Voltage		$V_{RMS}$	14	21	28	56	70	105	150	V
Maximum DC Blocking Voltage		$V_{DC}$	20	40	60	80	100	150	200	V
Maximum Average Forward Rectified Current at TL = 110°C		I <sub>F(AV)</sub>	1					Α		
Peak Forward Surge Current 8.3ms Single Half Sine -Wave Superimposed on Rated Load		I <sub>FSM</sub>	30					Α		
Maximum Instantaneous Forward Voltage at 1.0A		V <sub>F</sub>	0.	55	0.7	0.	85	0.	95	V
Maximum DC Reverse Current at	T <sub>A</sub> =25°C	I <sub>R1</sub>	0.5 0.1			.1	mA			
Rated DC Blocking Voltage	TA=100°C	I <sub>R2</sub>	20 10		2	2	mA			
Operating Junction and Storage Temperature Range		$T_{j},T_{stg}$	-55 to +150				°C			
THERMAL CHARACTERISTICS										
Thermal Resistance Junction to Ambient <sup>1</sup>		$R_{\theta(j-a)}$	88				°C/W			

#### Note:

- 1. P.C.B. mounted with 5.0\*5.0mm Copper Pad Area
- 2.Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.







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#### TYPICAL CHARACTERISTICS CURVES

Fig. 1. Forward current derating Curve AVERAGE FORWARD RECTIFIED CURRENT, AMPERES 1.0 0.8 ١ 0.6 0.4 SK12FL-SK16FI SK18FL-SK120F 0 150

Fig. 3. Typical Reverse Characteristics 100 10

90

120

150

INSTANTANEOUS REVERSE CURRENT, MICROAMPERES 0.01 0.0010 30 PERCENT OF PEAK REVERSE VOLTAGE,%

0.1

Fig. 2. Maximum Non-repetitive peak Forward surge current

AMBIENT TEMPERATURE, °C

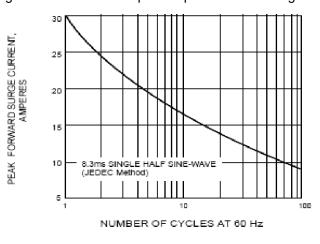
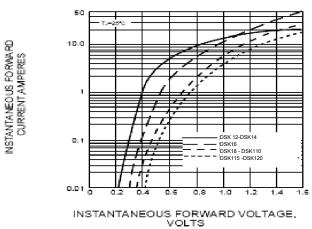


Fig. 4. Typical Transient Thermal Impedence 100 TRANSIENT THERMAL IMPEDANCE. 10 0.1 0.01 0.1 100

t,PULSE DURATION,sec.

Fig. 5. Typical instantaneous Forward Characteristics





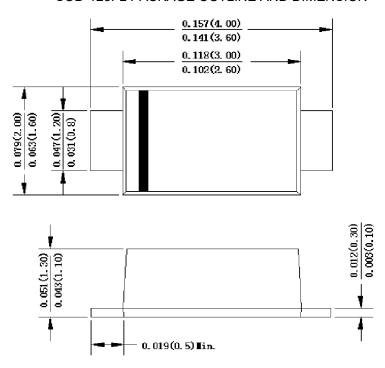






## **PACKAGE DETAILS**

## SOD-123FL PACKAGE OUTLINE AND DIMENSION



All dimensions are in inches(mm)







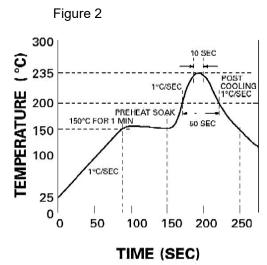
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#### **Recommended Reflow Solder Profiles**

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.



# Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System		
Average Ramp-Up Rate	~3°C/second	~3°C/second		
Preheat				
– Temperature Range	150-170°C	150-200°C		
– Time	60-180 seconds	60-180 seconds		
Time maintained above:				
– Temperature	200°C	217°C		
– Time	30-50 seconds	60-150 seconds		
Peak Temperature	235°C	260°C max.		
Time within +0 -5°C of actual Peak	10 seconds	40 seconds		
Ramp-Down Rate	3°C/second max.	6°C/second max.		





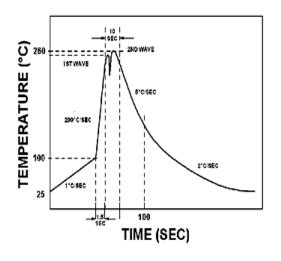


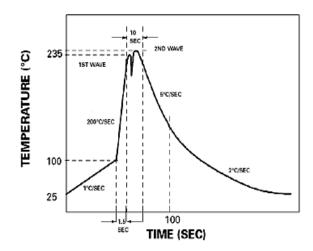
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#### **Recommended Wave Solder Profiles**

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





#### **Wave Profiles in Tabular Form**

Profile Feature	Sn-Pb System	Pb-free System			
Average Ramp-Up Rate	~200°C/second	~200°C/second			
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec			
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp			
Peak Temperature	235°C	260°C max.			
Time within +0 -5°C of actual Peak	10 seconds	10 seconds			
Ramp-Down Rate	5°C/second max.	5°C/second max.			







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# Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

#### **Shelf Life of CDIL Products**

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

#### Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start.

For this, the following JEDEC table may be referred:

JEDEC MSL Level				
Level	Time	Condition		
1	Unlimited	≤30 °C / 85% RH		
2	1 Year	≤30 °C / 60% RH		
2a	4 Weeks	≤30 °C / 60% RH		
3	168 Hours	≤30 °C / 60% RH		
4	72 Hours	≤30 °C / 60% RH		
5	48 Hours	≤30 °C / 60% RH		
5a	24 Hours	≤30 °C / 60% RH		
6	Time on Label(TOL)	≤30 °C / 60% RH		









#### **Customer Notes**

#### **Component Disposal Instructions**

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

#### Disclaimer

The product information and the selection guides facilitate selection of the CDIL's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



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